

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-12. (Previously Cancelled)

13. (Previously Presented) Compliant substrate according to claim 35, wherein said bonding interface is an interface resulting from a surface preparation and/or an interface resulting from a heat treatment and/or an interface resulting from a creation of defects.

14. (Previously Presented) Compliant substrate according to claim 13, wherein said surface preparation is a control of roughness and/or hydrophylia.

15. (Previously Presented) Compliant substrate according to Claim 35 where said structure also comprises at least one intermediate layer between the thin layer and the carrier.

16. (Previously Presented) Compliant substrate according to claim 15, wherein the intermediate layer is a metal layer or metal alloy layer.

17. (Previously Presented) Compliant substrate according to claim 15, wherein said at least one intermediate layer is formed such that it comprises non-homogeneities.

18-34. (Previously Cancelled)

35. (Previously Presented) Compliant substrate comprising a carrier and a structure comprising at least one thin layer, the structure being bonded on a surface of said carrier by molecular adhesion to constitute a bonding interface whose bonding energy is controlled to permit absorption, in whole or in part by the bonding interface, of stresses brought to said compliant substrate.

36-50. (Previously Cancelled)

51. (Currently Amended) Compliant substrate according to claim 35, wherein said stresses are brought by a hetero-epitaxial growth ~~realized~~ formed on the thin layer.

52. (Previously Presented) Compliant substrate according to claim 35, wherein the carrier comprises at least one intermediate layer joined to said carrier, the bonding interface being located between said structure and said at least one intermediate layer.

53. (Previously Cancelled)

54. (Previously Presented) Compliant substrate comprising:
a carrier having a first thin layer; and
a structure comprising a second thin layer, the structure being bonded on the first thin layer of said carrier by molecular adhesion to form a bonding interface whose bonding energy is

controlled to permit absorption, in whole or in part by the bonding interface, of stresses brought to said compliant substrate.